IEEE 802.3 400 Gb/s/Lane Signaling Study Group meeting

May 2026 Interim Hybrid Meeting
Munich, Germany (all times MESZ)
Meeting Minutes, Prepared by Beth Kochuparambil

Day 1 – May 11, 2026

802.3 Working Group Chair, David Law, called the meeting to order at 8:30am and welcomed participants to the 2026 May Interim.

He reminded participants that the IEEE 802.3 rules state that the Study Group Chair and Vice Chair are appointed by the Working Group Chair and confirmed by the Study Group.

Law appointed Kent Lusted as the IEEE 802.3 400 Gb/s/lane Study Group Chair and Mark Nowell as the IEEE 802.3 400 Gb/s/lane Study Group Vice Chair. Beth Kochuparambil was appointed as the IEEE 802.3 400 Gb/s/lane Study Group Recording Secretary.

Motion #1

Move to confirm Kent Lusted as the IEEE 802.3 400 Gb/s/lane Study Group Chair.
Move: A. Healey
Second: M. Dudek
The motion requires >= 75%, by rule, to pass.
Passed by unanimous consent at 8:36am

Motion #2

Move to confirm Mark Nowell as the IEEE 802.3 400 Gb/s/lane Study Group Vice-Chair.
Move: E. Opsasnick
Second: J. D'Ambrosia
The motion requires >= 75%, by rule, to pass.
Passed by unanimous consent at 8:38am

8:39am – The meeting was handed over to Kent Lusted as IEEE 802.3 400 Gb/s/lane Study Group Chair.

Presentation #1 Agenda and General Information

Presenter: Kent Lusted
https://www.ieee802.org/3/400GPL/public/2605/agenda_400GPL_01b_2605.pdf

The Chair reminded participants to declare their affiliation in the online meeting tool. Failure to do so would result in expulsion from the meeting. He also reminded participants that registration is required for this meeting.

The Chair asked if there were any modifications to the agenda (see slide #4) . He noted that P802.3dj needs more time for comment resolution, so would drive to wrap up our Study Group meeting by the end of Monday. There were no modifications requested. There were no objections. Agenda approved.

The Chair pointed to the minutes from a recent Study Group Ad Hoc (see slide #5) stating that he, nor Kochuparambil, received feedback on the minutes, and none brought up on the floor. The Chair asked if there was opposition to approving the minutes. No one objected. Minutes approved

The Chair reminded participants to follow the meeting decorum rules. The Chair asked for members of the press to identify themselves. No one identified as such.

The Chair expressed the goals for the meeting (see slide #12) and ground rules.

The Chair stated that attendance will be taken via IMAT and noted that it counted towards IEEE 802.3 Working Group voting membership and provided the link to mark one's attendance.

The Chair presented the second slide of the IEEE SA Pre-PAR Patent Policy slides (see slide #25). He did a call for Potentially Essential Patents, and no one came forward.

The Chair presented the second slide of the IEEE SA Copyright Policy slides (see slide #27). He noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

The Chair reminded participants of the IEEE Code of Ethics and Conduct (see slide #29). He noted "All participants in IEEE-SA activities are expected to adhere to the core principles underlying the IEEE Code of Ethics and IEEE Code of Conduct".

There were audio issues online. A reminder was given that the meeting is a "hybrid meeting with remote attendance at best effort" as announced by the Chair in the meeting announcement. Efforts were made to improve audio.

The Chair presented the second slide (see slide #30) of the IEEE SA Participation Policy slides. The Chair noted – “Participants in the IEEE-SA “individual process” shall act independently of others, including employers. By participating in standards activities using the “individual process”, you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.”

The Chair presented the third slide (see slide #31) of the IEEE SA Participation Policy. Chair noted that IEEE-SA standards activities should allow the fair & equitable consideration of all viewpoints, and The IEEE-SA Standards Board Bylaws (clause 5.2.1.3) specifies that “the standards development process shall not be dominated by any single interest category, individual, or organization”.

The Chair noted the IEEE Ethics Reporting Line (see slide #33) to the participants.

The Chair asked if any clarification was needed on IEEE SA Policies. There was none.

Break to work on audio issues. Meeting resumed 9:10am

The Chair reminded participants to declare their affiliation in the online meeting tool. Failure to do so would result in expulsion from the meeting.

9:11am – The meeting was handed over to Mark Nowell as IEEE 802.3 400 Gb/s/lane Study Group Vice-Chair.

Presentation #2 400GPL Timeline Considerations

Presenter: Kent Lusted
https://www.ieee802.org/3/400GPL/public/2605/lusted_400GPL_01_2605.pdf

Lusted clarified that the Task Force, should it be approved, would run longer than shown in the presented slides. He recommended participants look at the proposed PAR documentation for full project timeline.

9:19am – The meeting was handed back to Kent Lusted as IEEE 802.3 400 Gb/s/lane Study Group Chair.

Presentation #3 Study Group Nomenclature

Presenter: Mark Nowell
https://www.ieee802.org/3/400GPL/public/2605/nowell_400GPL_01_2605.pdf

The Chair gave individuals time to fill out IMAT for attendance. No one indicated needing more time.

Presentation #4 BER Objective for 400 Gb/s per lane PHYs

Presenter: Matt Brown
https://www.ieee802.org/3/400GPL/public/2605/brown_400GPL_01b_2605.pdf

Break. Meeting resumed at 10:33am

Presentation #5 Proposed SMF Objectives for 400GPL

Presenter: Brian Welch
https://www.ieee802.org/3/400GPL/public/2605/welch_400GPL_01b_0526.pdf

The Chair gave individuals time to fill out IMAT for attendance. No one indicated needing more time.

Presentation #6 400GPL Proposed AUI Objectives

Presenter: Matt Brown
https://www.ieee802.org/3/400GPL/public/2605/brown_400GPL_02c_2605.pdf

Presentation #7 Proposed Copper Cable Objectives

Presenter: Beth Kochuparambil
https://www.ieee802.org/3/400GPL/public/2605/kochuparambil_400GPL_01c_2605.pdf

Additional supporters and clarifications added to slides 5 and 10, and updated to version _01c after the presentation.

Break. Meeting resumed at 1:37pm

Participants noted a window popped down from Closed Captioning (CC) in the Webex interface, Kochuparambil clarified that Webex tool allows a participant to have local live closed-captioning but that the Webex meeting settings do not allow saving CC or any transcript of the meeting.

The Chair reminded participants that the Study Group leadership was driving to close at the end of Monday.

Motion #3

Move to adopt the following objectives:

- Support full-duplex operation only
- Preserve the Ethernet frame format utilizing the Ethernet MAC
- Preserve minimum and maximum FrameSize of current IEEE 802.3 standard

M: M. Nowell
S: J. Slavick
The motion was ruled technical and required >= 75% to pass
Passed by unanimous consent at 1:43pm

Motion #4

Move to adopt the following objective:

- Support a BER of better than or equal to 10^{-13} at the MAC/PLS service interface (or the frame loss ratio equivalent)

M: M. Brown
S: D. Ofelt
The motion was ruled technical and required >= 75% to pass
Passed by unanimous consent at 1:46pm

Motion #5

Move to adopt the following objectives:

- Define a physical layer specification that supports 400 Gb/s operation over 1 pair of SMF with lengths up to at least 500 m
- Define a physical layer specification that supports 800 Gb/s operation over 2 pairs of SMF with lengths up to at least 500 m
- Define a physical layer specification that supports 1.6 Tb/s operation over 4 pairs of SMF with lengths up to at least 500 m

M: J. Johnson
S: G. Mi
The motion was ruled technical and required >= 75% to pass
Passed by unanimous consent at 1:50pm

Motion #6

Move to adopt the following objectives:

- Support optional single-lane 400 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip applications
- Support optional two-lane 800 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip applications
- Support optional four-lane 1.6 Tb/s attachment unit interfaces for chip-to-module and chip-to-chip applications

M: M. Brown
S: A. Healey
The motion was ruled technical and required >= 75% to pass
Passed by unanimous consent at 1:53pm

Motion #7

Move to adopt the following objectives:

- Define a single-lane, 400 Gb/s PHY for operation over twin-axial copper cables with lengths up to at least 1 meter.
- Define a two-lane, 800 Gb/s PHY for operation over twin-axial copper cables with lengths up to at least 1 meter.
- Define a four-lane, 1.6 Tb/s PHY for operation over twin-axial copper cables with lengths up to at least 1 meter.

M: M. Nowell
S: N. Tracy
The motion was ruled technical and required >= 75% to pass
It was noted, in discussion, that active copper cable(s) could be a solution to this objective.
Passed by unanimous consent at 2:00pm

The Chair congratulated the study group for adopting objectives and reviewed next steps.

The Chair gave individuals time to fill out IMAT for attendance. No one indicated needing more time.

Presentation #8 Proposed CSD Responses for 400GPL Study Group

Presenter: Mark Nowell
https://www.ieee802.org/3/400GPL/public/2605/nowell_400GPL_02b_2605.pdf

Edits were made to the text and updated after the presentation to 02b

Presentation #9 Proposed DRAFT IEEE P802.3dv PAR Responses

Presenter: John D'Ambrosia
https://www.ieee802.org/3/400GPL/public/2605/dambrosia_400GPL_01a_2605.pdf

Edits were made to the text and updated after the presentation to version _01a

Break. The meeting resumed at 3:50pm.

The Chair noted that the updated CSD responses presentation, the updated PAR response presentation, and PAR draft PDF document that was output from My Project tool were posted.

Motion #8

Move to adopt the CSD "Managed Objects", "Coexistence", "Broad Market Potential", "Compatibility", "Distinct Identity", "Technical Feasibility", and "Economic Feasibility" responses, as per nowell_400GPL_02b_2605.pdf
M: M. Nowell
S: D. Ofelt
The motion was ruled technical and required >= 75% to pass
Passed by unanimous consent at 3:56pm

Motion #9

Move to adopt the PAR responses in Draft_P802.3dv_260511.pdf
M: J. D'Ambrosia
S: M. Choudhury
The motion was ruled technical and required >= 75% to pass
Passed by unanimous consent at 4:00pm

The Chair noted the time and volume of presentations remaining to review and asked if there was objection to conclude the Study Group meeting today thereby giving the Tuesday AM sessions to P802.3dj. He noted that this may cause several presentations to get bumped to future ad hocs. No objection voiced.

Presentation #10 How NPO May Fit in IEEE 400GPL

Presenter: Guangcan Mi
https://www.ieee802.org/3/400GPL/public/2605/mi_400GPL_01a_2605.pdf

Presentation #11 Package-Level Considerations for 400GPL Feasibility

Presenter: Toshiaki Sokai
https://www.ieee802.org/3/400GPL/public/2605/sakai_400GPL_01a_2605.pdf

The Chair gave individuals time to fill out IMAT for attendance. No one indicated needing more time.

Presentation #12 Consideration on NPO and CPO at 400Gbps/lane

Presenter: Runlong Hu
https://www.ieee802.org/3/400GPL/public/2605/wang_h_400GPL_01a_2605.pdf

Presentation #13 The consideration on modulation formats of 400Gbps per lane optical signal

Presenter: Li Xu
https://www.ieee802.org/3/400GPL/public/2605/fan_x_400GPL_01a_2605.pdf

Thanks were given to Tom Berger & Maxim Kuschnerov for being willing to defer their presentation to Ad Hoc, so we could give it due time.

The Chair gave closing announcements

- Great work everyone! A big milestone was reached this meeting
- Next step was to request PAR approval in the July Plenary review cycle
- 2 Ad Hocs are tentatively scheduled for June (potentially June 11 and June 30); Participants were encouraged to watch the reflector for final dates/times.

John D'Ambrosia expressed gratitude for the additional time for P802.3dj comment resolution and clarified calendar meetings and expected topics for May 12.

The Chair noted that business was concluded and the meeting cancelled for Tuesday, May 12.

Meeting adjourned at 5:49pm MESZ

Attendance, as captured from IMAT

Name	Employer	Affiliation
Ahuja, Ramanjit	ON Semiconductor	ON Semiconductor
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Alloin, Laurent		Ciena Corporation
Baggett, Tim	Microchip Technology, Inc.	Microchip Technology, Inc.
Bang, Juneho		Huawei Technologies Duesseldorf GmbH
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
Brown, Matthew	Alphawave Semi	Qualcomm
Bruckman, Leon	NVIDIA	NVIDIA
Brychta, Michal	Analog Devices Inc.	Analog Devices Inc.
Budweiser, Karl		BMW AG; BMW Group
Calvin, John	Keysight Technologies	Keysight Technologies
Chen, Chan	Self Employed	Independent/AOI
CHENG, WEICHANG	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
cheng, weiqiang	China Mobile Limited	China Mobile Limited
cheng, xiaoyue		Infineon Technologies
Chini, Ahmad	Broadcom Corporation	Broadcom Corporation
Choudhury, Golam	Genuine Optics	Genuine Optics
Cole, Christopher R	Finisar Corporation	Coherent Corp.
Cox, Ian		Broadcom Corporation
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dai, Shaoan		Infineon Technologies

Dar, Marva	TE Connectivity	TE Connectivity
Dawe, Piers J G	NVIDIA	Nvidia
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.
Donahue, Curtis	Rohde & Schwarz	Rohde & Schwarz
Dsilva, Hansel		Amphenol Corporation
Dudek, Michael	Marvell	Marvell
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Elangovan, Vivekanandh	Infineon Technologies	Infineon Technologies
Engenhardt, Klaus		Teradyne, Inc. & Quantifi Photonics
Estrakh, Daniel	Valens Semiconductor	Valens Semiconductor
Fan, Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Ganesan, Aravind	Texas Instruments Inc.	Texas Instruments Inc.
Gareau, Sebastien		Ciena Corporation
Gauthier, Claude	NXP Semiconductors	NXP Semiconductors
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Gupta, Ajeya		General Motors Company
Hand, Steven		Nokia
Haydt, Mary Sue	Microchip Technology, Inc.	Microchip Technology, Inc.
HE, MICHAEL	TeraHop Pte. Ltd.	TeraHop Pte. Ltd.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Hogenmueller, Thomas	Robert Bosch GmbH	Robert Bosch GmbH
Hon, Kam Yan		Cisco Systems, Inc.
Hu, Runlong		China Mobile Communications Group Co.,Ltd; China Mobile Communications Group Co.,Ltd
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Irwin, Scott	MoSys, Inc.	ADTRAN Inc.
Isono, Hideki	Furukawa FITEL Optical Components Limited	Furukawa FITEL Optical Components
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Iwasaki, Yutaka	Hirose Electric Co.,Ltd.	Hirose Electric Co., Ltd.
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
Jochim, Markus	General Motors Company	General Motors Company
Johnson, John	Broadcom Corporation	Broadcom Corporation
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRTO	Dexerials	Dexerials
Kim, DoKyun	LG ELECTRONICS	LG ELECTRONICS
Kim, Gyudong	Analog Devices Inc.	Analog Devices Inc.
Kimber, Eric	Semtech Ltd	Semtech Ltd

Kleinwaechter, Mathias	in-tech GmbH	in-tech GmbH
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Kondo, Taiji	Dexerials Corporation	Dexerials Corporation
Landry, Gary	Coherent Corp.	Texas Instruments Inc.
Lasry, Ariel	Qualcomm Technologies, Inc	Qualcomm Technologies, Inc
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lee, Ching-Yen		Realtek Semiconductor Corp.
Lessard, Stephane	Ericsson AB	Ericsson AB
Lewis, David	SPECIPHY / Lumentum	SPECIPHY, LUMENTUM
Li, jiaqi		Huawei Technologies Co., Ltd
Li, Jieyu		China Mobile Communications Group Co.,Ltd; China Mobile Communications Group Co.,Ltd
Li, Jing	YOFC	YOFC
Li, Mike-Peng	Altera Corporation	Intel Corporation
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lin, YK	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Lo, William	Axonne Inc.	Axonne Inc.
lu, chao	BMW Group	BMW Group
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Lyu, Yunping(Lily)	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Maguire, Valerie	Copperopolis	Copperopolis (aff'l with CME Consulting)
Maki, Jeffery	Hewlett Packard Enterprise	Hewlett Packard Enterprise

Maniloff, Eric	Ciena Corporation	Ciena Corporation
Mascitto, Marco	Infinera Canada Inc.	Nokia
Matheus, Kirsten	BMW Group, VDA	BMW Group
Matuz, Balazs		Huawei Technologies Duesseldorf GmbH
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Miskho, Michael		Analog Devices Inc.
Mitcheltree, Tom	US Conec, Ltd.	US Conec, Ltd.
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Mueller, Thomas	Rosenberger	Rosenberger
Muller, Shimon	Enfabrica Corp.	Enfabrica
Muma, Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
MURAKAMI, YUKI	1Finity	1Finity
Murray, Brian	Analog Devices Inc.	Analog Devices Inc.
Murty, Ramana	Broadcom Inc.	Broadcom Corporation
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
Nakamoto, Edward	Spirent Communications	VIAVI Solutions
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Nielsen, Jannik		Huawei Technologies Duesseldorf GmbH
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation
Noujeim, Leesa	Google	Google
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Omori, Kumi	NEC Corporation	NEC Corporation

Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Osorio, Luz		Nokia
Pal, Debajyoti		ON Semiconductor
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Pandey, Sujan	Velinktech	Velinktech
Park, Pusik		Korea Electronics Technology Institute (KETI); Korea Electronics Technology Institute (KETI); Korea Electronics Technology Institute (KETI); Korea Electronics Technology Institute (KETI)
Parkholm, Ulf	Telefon AB LM Ericsson	Ericsson AB
Parsons, Earl	CommScope, Inc.	CommScope, Inc.
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
Peng, BC		MediaTek Inc.
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Pischl, Neven	Broadcom Corporation	Broadcom Corporation
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ransford, Michael		Corning Incorporated
Razavi, Alireza	Marvell	Infineon Technologies
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rodes, Roberto	II-VI	II-VI
Sakai, Toshiaki	Socionext Inc.	socionext
Schedl, Anton	BMW Group	BMW Group
Schreiner, Stephan	Rosenberger Hochfrequenztechnik GmbH & Co. KG	Rosenberger
Sekel, Steve	Wilder Technologies	wilder Technologoeis
Shah, Anup	Siemens Corporation	Siemens EDA

Shakiba, Mohammad	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada; Huawei Technologies Co., Ltd
Sharma, Rohit		Molex Incorporated
Sheffi, Nir	Alphawave	Alphawave
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Upscale AI
Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sommers, Scott	Molex LLC	Molex Incorporated
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
Srivastava, Atul	NEL-America	NTT Electronics
Strohmeier, Heiko	Robert Bosch GmbH	Robert Bosch GmbH
Sun, jingcong	Motorcomm Electronic Technology Co	Motorcomm Electronic Technology Co
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Nokia
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	1FINITY
Tan, Yuxuan	Motorcomm	Motorcomm
Tanc, Ahmet		NXP Semiconductors; NXP Semiconductors
Tanz, Simon		BMW AG; BMW Group
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT
Torres, Luisma	Knowledge Development for POF SL	KD
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Vanderlaan, Paul	UL Solutions	Panduit Corp.
Vitali, Marco	Sicoya	fJscaler

Voss, Robert	Panduit Corp.	Panduit Corp.
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Shun-Sheng	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.
Wang, Tongtong	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Weaver, James	Arista Networks	Arista Networks
Wei, Terry		Analog Devices Inc.
Welch, Brian	Cisco Systems, Inc.	Luxtera
Wettlin, Tom		Huawei Technologies Duesseldorf GmbH
Wienckowski, Natalie	IVN Solutions LLC	IVN Solutions LLC; Ethernovia
Wig, Timothy	Samtec, Inc.	Samtec, Inc.
Wingrove, Michael	Ciena Corporation	Ciena Corporation
Withey, James	Fluke Corporation	Fluke Corporation
Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
xu, wenxiong	HG Genuine	HGGenuine
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yang, Penglin	Hygon Information Technology Co., Ltd.,	Hygon Information Technology Co,. Ltd.
YANG, Yumeng	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
ZHANG, KAN		China Mobile (Chengdu) Information and Telecommunication
Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zivny, Pavel	Lumilens	Lumilens

Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd